

Final Product Change Notification

Issue Date:18-Feb-2014Effective Date:19-May-2014

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201310001F01



QUALITY

Change Category

[X] Wafer Fab process [X] Wafer Fab materials [] Wafer Fab location [] Assembly Process [] Assembly Materials [] Assembly Location

[] Product Marking [] Electrical spec./Test coverage

- [] Design
- [] Mechanical Specification
- [] Packing/Shipping/Labeling

Release of 8 inch wafer diameter for medium power and low VCEsat transistors

Details of this Change

Release of production using 8 inch wafer diameter for medium power, switching and low VCEsat (BISS) transistors in SOT89 and SOT96-1 (SO8) packages. In addition the thickness of the top metallisation of the affected BISS transistors will be adapted.

[] Test Location

Old products: Production using 6 inch wafer diameter, top side metallisation thickness 2.1µm (BISS transistors) Changed products: Production using 6 and 8 inch wafer diameter, top side metallisation thickness 2.1µm (BISS transistors with 6 inch wafer diameter) resp. 2.2µm (BISS transistors with 8 inch wafer diameter)

Production on 8 inch wafer diameter implies the use of the respective 8 inch wafer process technology.

Why do we Implement this Change

To increase flexibility and volume ramp-up.

Identification of Affected Products

The 8 inch products can be identified by a marker on the die surface.

Product Availability

Sample Information

Samples are available upon request Latest sample request date for PCN samples is March 19, 2014.

Production

Planned first shipment 01-May-2014

Impact

no impact to the product's functionality anticipated.

Die size and active area remain unchanged. No change on external dimensions or mechanical behavior. Electrical parameters are unchanged (in specification and with the same distribution).

Disposition of Old Products

Supply using 6 inch wafer will be continued.

Additional information

Affected products and sales history information Self qualification

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 20-Mar-2014.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please <u>contact NXP "Global Quality Support</u> <u>Team"</u>.

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly: **Name** GA Customer Support

e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

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NXP Quality Management Team.

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